

Product Data Sheet

hm2.0 lower shield plate, Type D,
Part No. 246-11600-1

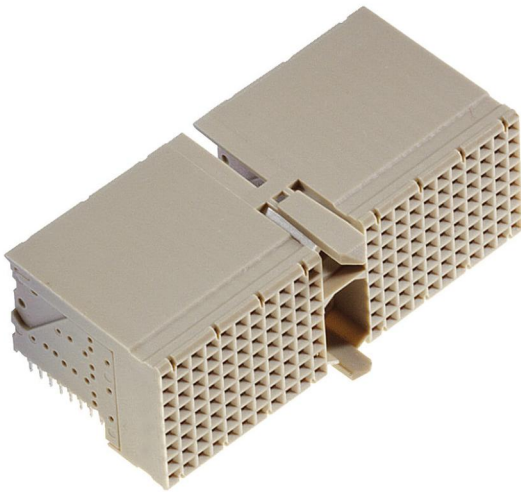


Illustration similar



Perpendicular



Press-fit

- 22 contacts
- Connector length: 3.4 mm
- for PCB thickness of at least 1.44 mm
- Tested in accordance with IEC 61076-4-101



» to product on www.ept.de



» to product group hm 2.0

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Technical Specifications

Basics

Specification	IEC 61076-4-101
Performance Level	2
No. of Contacts	22
Termination Technology	Press-fit technology
Termination Length	3.4 mm
Operating Temperature Range	-55°C to +125°C

Material

Contact Material	Bronze
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Mechanical

Pitch	2.0 mm
Mating Force per Pin	Shielding: max. 1 N
Separating Force per Pin	Shielding: min. 0.15 N
Durability	> 250 insertion cycles

Electrical

Operational Current	1.5 A at +20°C, 1.0 A at +70°C
Contact Resistance	max. 20 mΩ
Insulation Resistance	at least 10 ⁴ MΩ
Test Voltage	750 V r.m.s.
Data Transfer Rate	3.125 Gbit/s

Approval / Compliance

Environment	RoHS compliant
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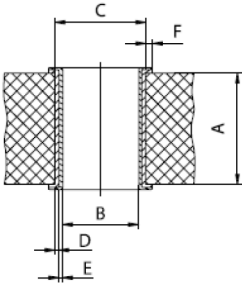
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Schicht
Nennloch	Ø 0.6 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	max. 1.5 µm; chem. Sn Leiterplatten
F Restring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nennloch	Ø 0.6 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Restring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nennloch	Ø 0.6 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	OSP*, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Restring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nennloch	Ø 0.6 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	HAL Sn, 5 - 15 µm
F Restring	min. 0.1 mm

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Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)